Surface Mount Standard Recovery Power Rectifier

SMA Power Surface Mount Package

Features construction with glass passivation. Ideally suited for surface mounted automotive applications.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Stable, High Temperature, Glass Passivated Junction
- These Devices are Pb-Free and are RoHS Compliant

Mechanical Characteristics

- Case: Molded Epoxy Epoxy meets UL 94 V-0 @ 0.125 in
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces are Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 seconds in Solder Bath
- Polarity: Band in Plastic Body Indicates Cathode Lead
- Marking: MRA4003T3G = R13

MRA4004T3G = R14

MRA4005T1G = R15

MKA400311G = K13

MRA4005T3G = R15MRA4006T3G = R16

MRA4007T3G = R17



ON Semiconductor®

http://onsemi.com

STANDARD RECOVERY RECTIFIERS 1.0 AMPERES 300-1000 VOLTS



CASE 403D SMA

MARKING DIAGRAM



R1x = Specific Device Code

A = Assembly Location

′ = Year

WW = Work Week

= Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the ordering information section on page 4 of this data sheet.

MAXIMUM RATINGS

		Value					
Rating	Symbol	MRA4003	MRA4004	MRA4005	MRA4006	MRA4007	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	300	400	600	800	1000	Volts
Avg. Rectified Forward Current (At Rated V _R , T _L = 150°C)	I _O	1				Amp	
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _L = 150°C)	I _{FRM}	2				Amps	
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I _{FSM}	30					Amps
Storage/Operating Case Temperature	T _{stg} , T _C	–55 to 150				°C	
Operating Junction Temperature	TJ	-55 to 175				°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1) Thermal Resistance, Junction-to-Ambient (Note 2)	R _{θJL} R _{θJA}	16.2 88.3	°C/W

ELECTRICAL CHARACTERISTICS

		Value		
Characteristic	Symbol	T _J = 25°C	T _J = 100°C	Unit
Maximum Instantaneous Forward Voltage (Note 3) (I _F = 1 A) (I _F = 2 A)	V _F	1.1 1.18	1.04 1.12	Volts
Maximum Instantaneous Reverse Current (at rated DC voltage)	I _R	10	50	μΑ

- 1. Minimum Pad Size
- 2. 1 inch Pad Size
- 3. Pulse Test: Pulse Width \leq 250 μ s, Duty Cycle \leq 2%.

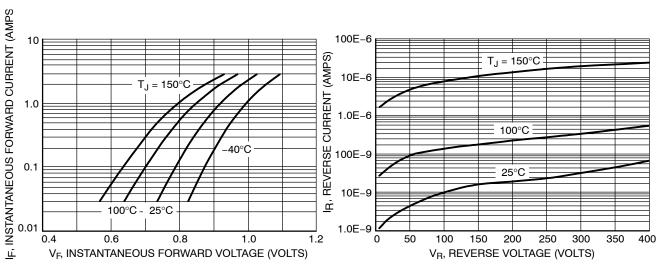


Figure 1. Typical Forward Voltage

Figure 2. Typical Reverse Current

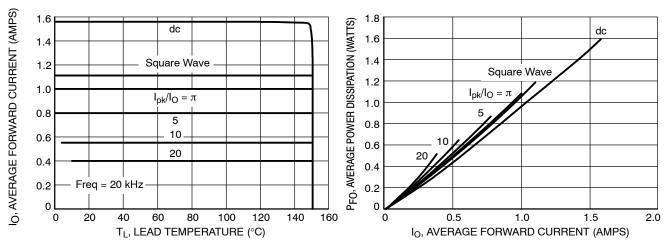


Figure 3. Current Derating per Leg

Figure 4. Forward Power Dissipation per Leg

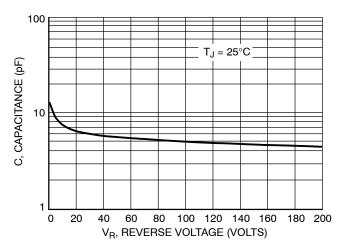


Figure 5. Capacitance

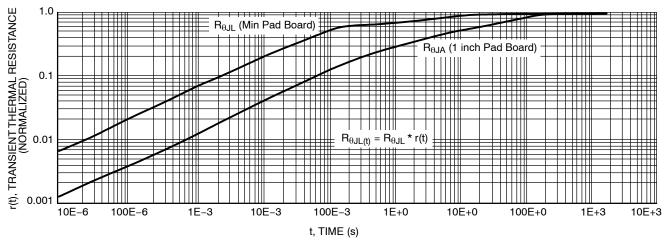


Figure 6. Thermal Response

ORDERING INFORMATION

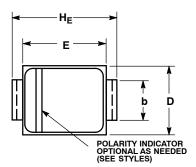
Device	Package	Shipping†
MRA4003T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4004T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4005T1G	SMA (Pb-Free)	1500/Tape & Reel
MRA4005T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4006T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4007T3G	SMA (Pb-Free)	5000/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SMA

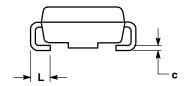
CASE 403D-02 **ISSUE F**

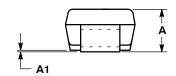


NOTES:

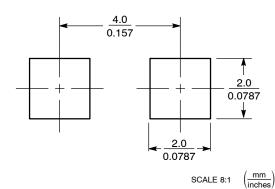
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- 403D-01 OBSOLETE, NEW STANDARD IS 403D-02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.97	2.10	2.20	0.078	0.083	0.087
A1	0.05	0.10	0.15	0.002	0.004	0.006
b	1.27	1.45	1.63	0.050	0.057	0.064
С	0.15	0.28	0.41	0.006	0.011	0.016
D	2.29	2.60	2.92	0.090	0.103	0.115
E	4.06	4.32	4.57	0.160	0.170	0.180
HE	4.83	5.21	5.59	0.190	0.205	0.220
L	0.76	1.14	1.52	0.030	0.045	0.060





SOLDERING FOOTPRINT*



SCALE 8:1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its partner rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada

Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative